

MF-13

Notice of References Cited	Application No. 09/731,726	Applicant(s) Shimizu et al	
	Examiner S. Ip	Group Art Unit 1742	Page 1 of 1

U.S. PATENT DOCUMENTS

*	DOCUMENT NO.	DATE	NAME	CLASS	SUBCLASS
A	6160224	12/12/00	Ogashira et al	174	257
B					
C					
D					
E					
F					
G					
H					
I					
J					
K					
L					
M					

FOREIGN PATENT DOCUMENTS

*	DOCUMENT NO.	DATE	COUNTRY	NAME	CLASS	SUBCLASS
N	200015476	1/18/00	JP	Matsumoto et al	-	-
O	115725	4/30/81	PL	Kozlowski et al	-	-
P	409260427	10/3/97	JP	Akamatsu et al	-	-
Q						
R						
S						
T						

NON-PATENT DOCUMENTS

*	DOCUMENT (Including Author, Title, Source, and Pertinent Pages)	DATE
U	Arai, Susumu; Ihara, Yoshihiro; Kobayashi, Tsuyoshi, Sn-Ag-Cu alloy solder bump formation by electroplating, Symp. "Micro Joining Assem. Technol. Electron." (1999) 5 th 109-114	1999
V		
W		
X		

* A copy of this reference is not being furnished with this Office action.
(See Manual of Patent Examining Procedure, Section 707.05(a).)